

SMD2016



SMD Type, 6 V - 60 V

Standard

UL 1434 1st Edition
CSA C22.2 No. 0 CSA TIL No. CA-3A

Approvals

cULus Recognition
TÜV

Features

These devices offer a wide range of hold currents from 0.3 A to 2.0 A and voltages from 6 V to 60 V. The SMD2016 product line is suitable for high density circuit board applications in computers, telecommunications and general electronics. Suitable for reflow soldering.

Specifications

Packaging

A Blister tape and reel Ø 178 mm

Materials

Terminals: TF: Lead free plating

Max. Device Surface Temperature in Tripped State
125 °C

Operating / Storage Temperature

-40 °C to +85 °C (consider derating)

Humidity Ageing

+85 °C, 85 % R.H., 1000 hours, ± 5 % typical resistance change

Vibration

MIL-STD-883C, Method 2007.1, Condition A, no change

Thermal Shock

MIL-STD-202F, Method 107G
+85 °C to -40 °C 20 times, -30 % typical resistance change

Solderability

Meets EIA Specification RS186-9E,
ANSI/J-STD-002, Category 3
Reflow only

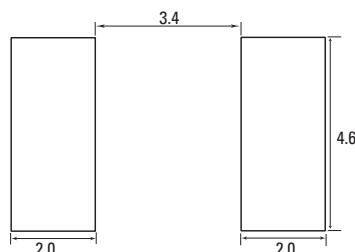
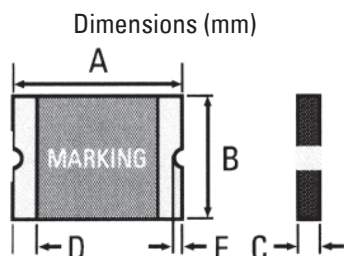
Solvent Resistance

MIL-STD-202, Method 215, no change

Marking

"P", Part Code

Solder pad Layout (mm)



Dimensions (mm)

Model	A		B		C		D	E		packaging quantity tape
	Min	Max	Min	Max	Min	Max	Min	Min	Max	
SMD2016P030TF	4.72	5.44	3.70	4.43	0.75	1.25	0.30	0.25	0.65	1,500
SMD2016P050TF	4.72	5.44	3.70	4.43	1.20	2.00	0.30	0.25	0.65	1,500
SMD2016P100TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	0.25	0.65	2,000
SMD2016P100TF/33	4.72	5.44	3.70	4.43	0.75	1.25	0.30	0.25	0.65	1,500
SMD2016P150TF	4.72	5.44	3.70	4.43	0.75	1.55	0.30	0.25	0.65	1,500
SMD2016P200TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	0.25	0.65	2,000

Permissible continuous operating current is ≤ 100 % at ambient temperature of 20 °C (68 °F).

Model	I _{hold} (A)	I _{trip} (A)	V _{max. dc} (V)	I _{max.} (A)	max. time to trip (s @ A)	P _{d max.} (W)	Resistance			Approvals	
							R _{min.} (Ω)	R _{typ.} (Ω)	R _{I max.} (Ω)		
SMD2016P030TF	0.30	0.60	60	20	3.00 @ 1.50	1.4	0.500	1.400	2.300	•	•
SMD2016P050TF	0.55	1.10	60	20	5.00 @ 2.50	1.4	0.200	0.700	1.000	•	•
SMD2016P100TF	1.10	2.20	15	40	0.50 @ 8.00	1.4	0.100	0.250	0.400	•	•
SMD2016P100TF/33	1.10	2.20	33	40	0.50 @ 8.00	1.4	0.100	0.250	0.400	•	•
SMD2016P150TF	1.50	3.00	15	40	1.00 @ 8.00	1.4	0.070	0.130	0.180	•	•
SMD2016P200TF	2.00	4.20	6	40	3.00 @ 8.00	1.4	0.048	0.070	0.100	•	•

NOTE:

I_{hold} = Hold current: maximum current device will pass without tripping in 20 °C still air.
I_{trip} = Trip current: minimum current at which the device will trip in 20 °C still air.
V_{max.} = Maximum voltage device can withstand without damage at rated current (I_{max.})
I_{max.} = Maximum fault current device can withstand without damage at rated voltage (V_{max.})

P_d = Power dissipated from device when in the tripped state at 20 °C still air.

R_{min.} = Minimum resistance of device in initial (un-soldered) state.

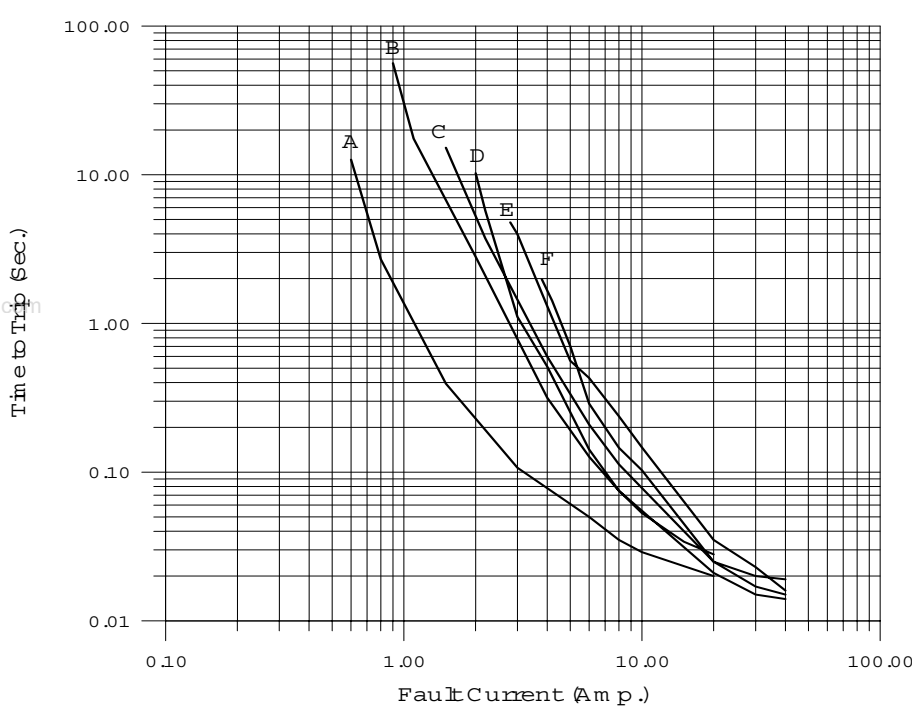
R_{I max.} = Maximum resistance of device at 20 °C measured one hour after tripping for 20 s.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame. Specifications are subject to change without notice

Order
Information

Qty.	Order- Number	Model	Packaging

SMD2016



Thermal Derating Chart

Model	Ambient Operation Temperature - I_{hold} (A)								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
SMD2016P030TF	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.18	0.14
SMD2016P050TF	0.93	0.80	0.65	0.50	0.38	0.32	0.25	0.19	0.09
SMD2016P100TF	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P100TF/33	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P150TF	2.26	2.00	1.76	1.50	1.24	1.13	1.00	0.87	0.68
SMD2016P200TF	2.80	2.50	2.19	2.00	1.84	1.74	1.50	1.34	1.14